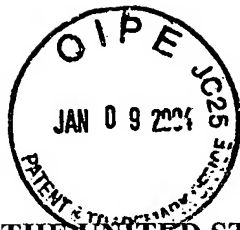


MICRON.133DV1



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Trivedi et al.
Appl. No. : 10/038,305
Filed : January 2, 2002
For : METHOD OF FORMING A
DUAL DAMASCENE
INTERCONNECT BY
SELECTIVE METAL
DEPOSITION (As Amended
Herewith)
Examiner : Thanh T. Nguyen
Group Art Unit : 2813

CERTIFICATE OF MAILING

I hereby certify that this correspondence and all marked attachments are being deposited with the United States Postal Service as first-class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on

January 6, 2004

(Date)

Adeel S. Akhtar

Adeel S. Akhtar, Reg. No. 41,394

AMENDMENT AND RESPONSE TO OFFICE ACTION

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

In response to the Office Action mailed October 7, 2003 in the above-identified application, Applicants respectfully request full consideration of the remarks contained herein.

Amendments to the Specification begin on page 2 of this paper.

A listing of the claims begins on page 3 of this paper.

Remarks/Arguments begin on page 5 of this paper.

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